

Appl. No. 09/843,630
Response to Office Action of November 13, 2006
Amendment dated February 13, 2007

REMARKS

In response to the Examiner's office action dated November 13, 2006, Applicant hereby presents amended claims so that the Examiner may consider alternate definitions of the invention as disclosed in the specification. More specifically, Applicant has modified the independent claims to specify that the insulating layer/SiO₂ and the passivation layer are respectively formed over the electrode-containing side of the pseudo-wafer prior to dicing of the pseudo-wafer into individual chips. Advantageously, this desirably decreases the manufacturing costs because the insulating layer and passivation layer may be formed over a plurality of multi-chip modules at the same time via. Additionally, flux and solder can be formed for all of the connections of the plurality of multi-chip modules simultaneously by, for example, a printing method. (See paragraphs [0066] and [0067] of Applicant's disclosure).

Additionally, each of the chips utilized in the multi-chip module are pre-tested to be non-defective. As a result, defective chips are not processed to the point at which electrical interconnection structures are formed, and substantial manufacturing costs are saved (See paragraph [0071] of Applicant's disclosure).

Applicant respectfully submits that the prior art references of record, whether considered alone, or in combination, fail to either teach or suggest Applicant's presently claimed invention. More specifically, Applicant notes that the references upon which the Examiner has relied in rejecting the claims under 35 USC § 102 fail to anticipate the currently claimed invention. More specifically, neither Dando (U.S. Patent No. 5,863,813) nor Eichelberger (U.S. Patent No. 5,841,193) disclose, teach, or suggest all of the limitations of the currently amended claims. Accordingly, Applicants respectfully request that the 35 U.S.C. §102 rejections be withdrawn, and claims 4, 8, and 9 be placed into condition for allowance.

Feb 13 07 05:25p

Rockey Depke Lyons & Kitz

3124410764

p.8

Appl. No. 09/843,630
Response to Office Action of November 13, 2006
Amendment dated February 13, 2007

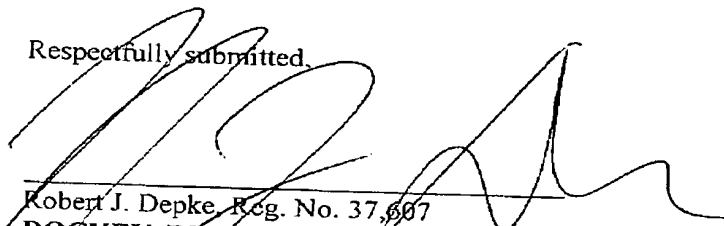
In regard to the Examiner's rejection of the claims under 35 U.S.C. §112, Applicant submits that the Examiner's rejection has been obviated by the attached Amendment. Accordingly, Applicants respectfully request that the Examiner's rejection be withdrawn, and claims 4 and 8 placed into condition for allowance.

In light of the foregoing, Applicant respectfully submits that there is no teaching or suggestion in the cited reference concerning the use of a dicing sheet as now specified in the claims. Accordingly, in light of the foregoing, Applicant respectfully submits that all claims now stand in a condition for allowance.

Date:

2/13/07

Respectfully submitted,



Robert J. Depke, Reg. No. 37,607
ROCKEY, DEPKE, LYONS & KITZINGER, LLC.
233 S. Wacker Drive, Suite 5450
Chicago, Illinois 60606
Tel: (312) 277-2006
Attorney for Applicant